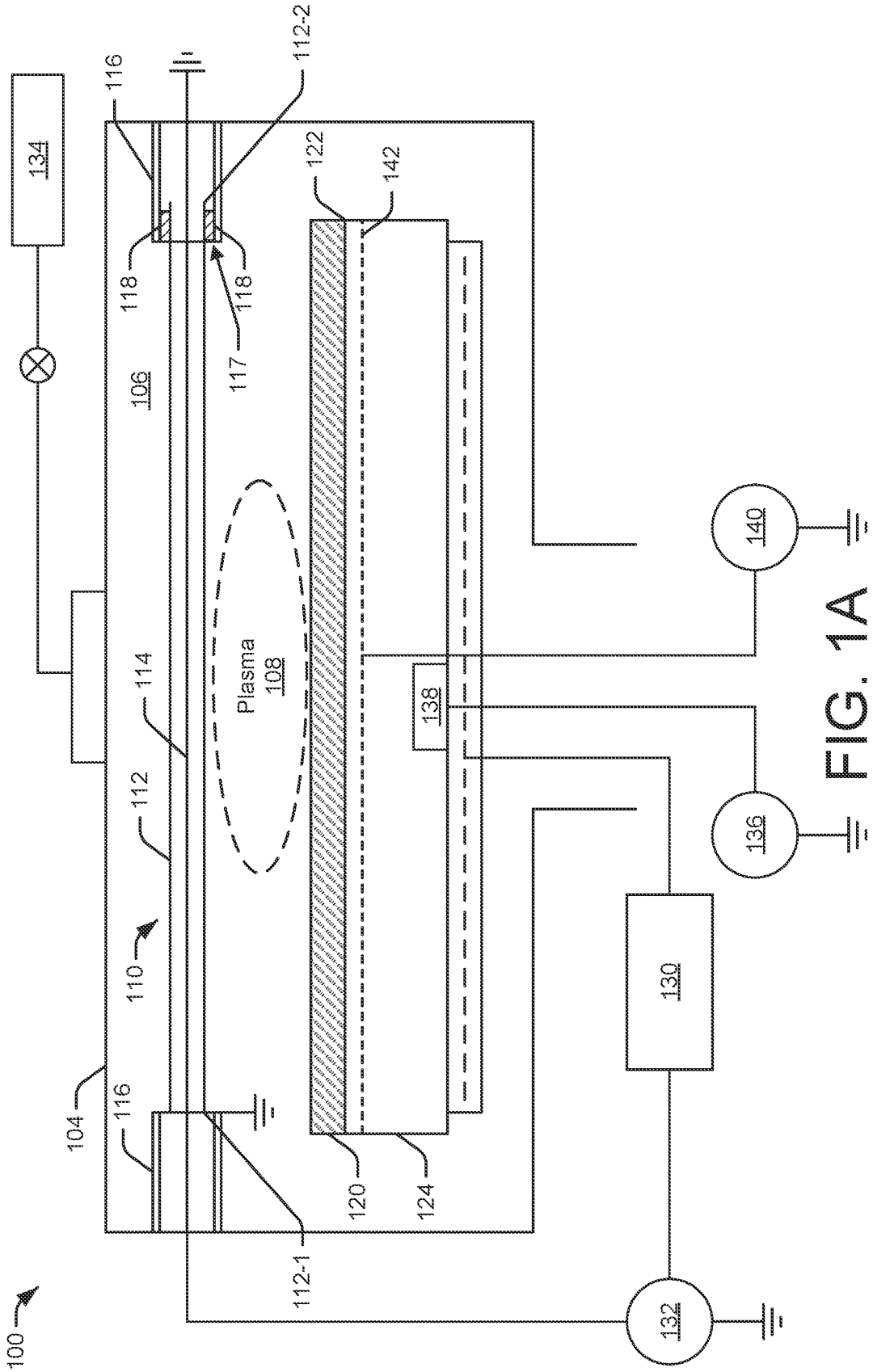

100
104
106
108
110
112
112-1
112-2
114
116
116
117
118
118
120
122
124
130
132
134
136
138
140
142
Plasma

FIG. 1A

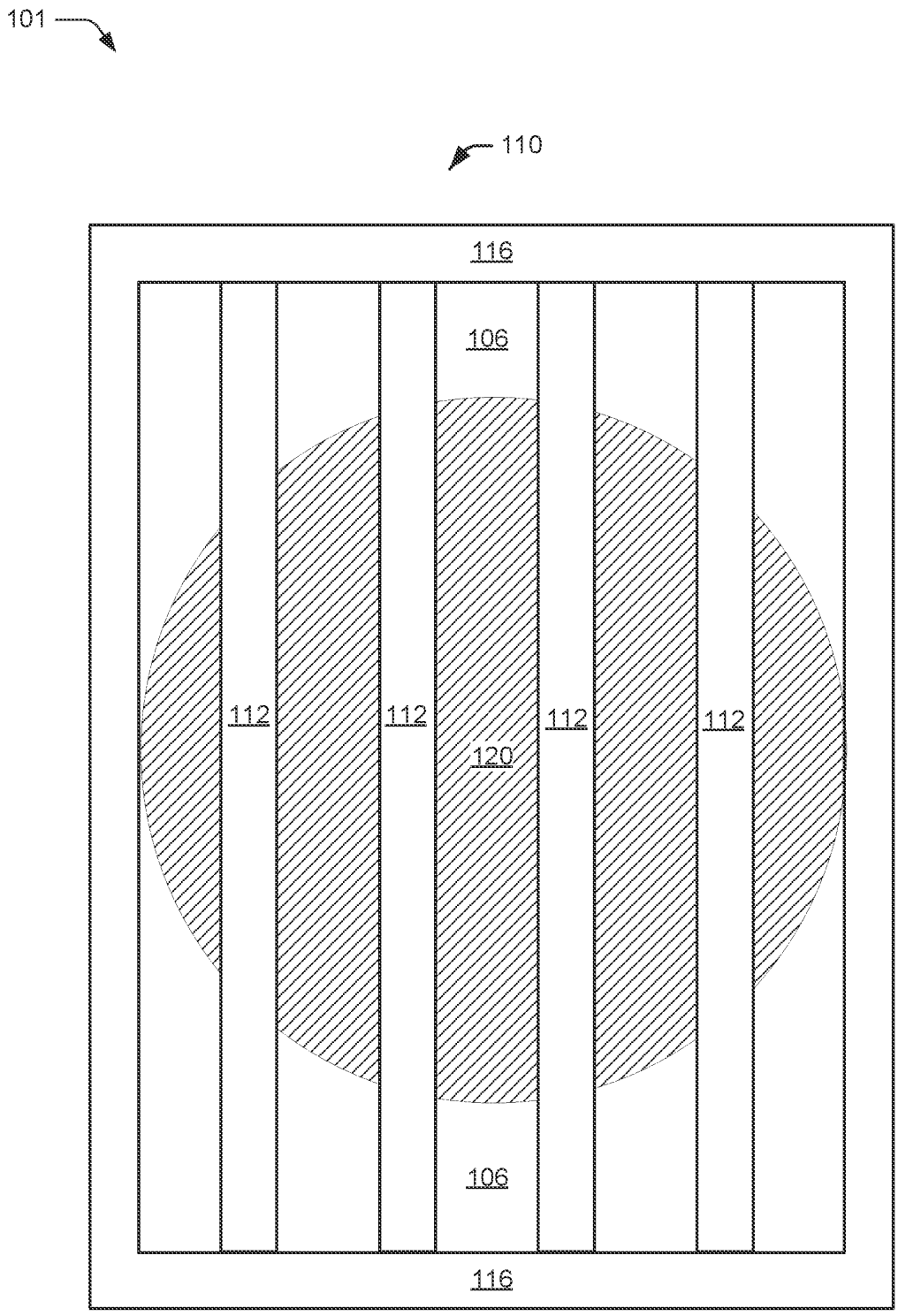


FIG. 1B

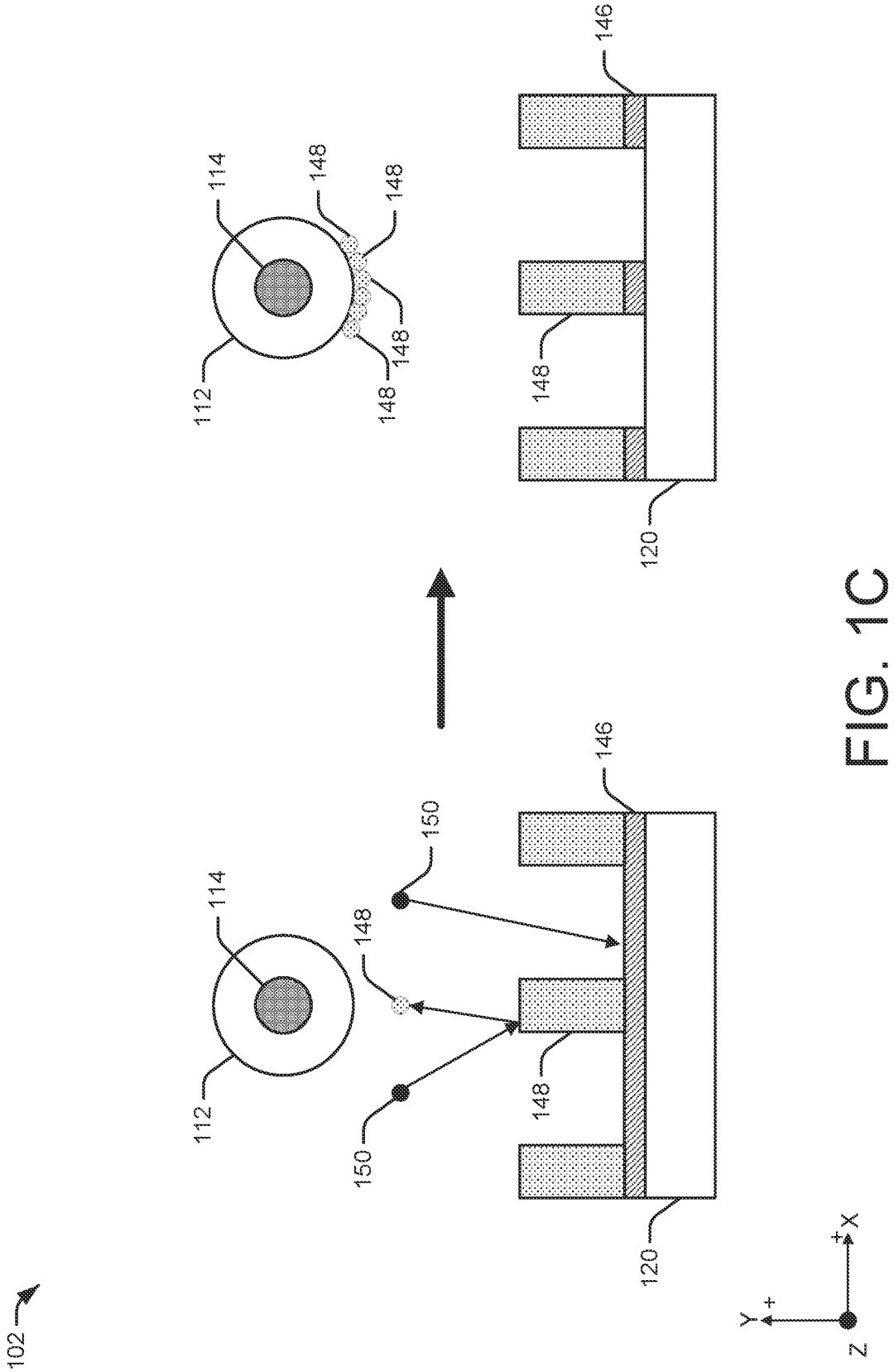


FIG. 1C

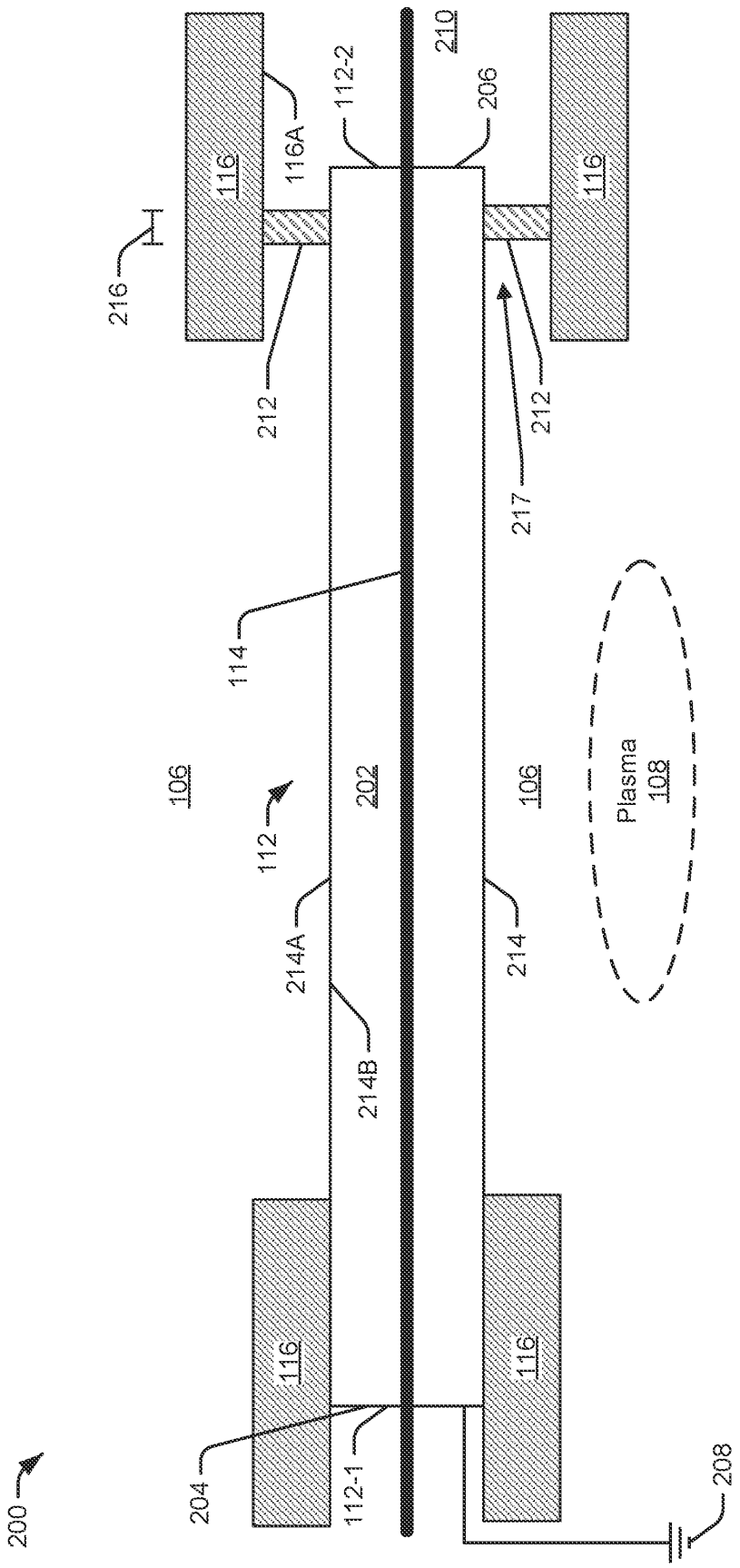

200
204
116
112-1
208
214B
214A
112
106
202
214
106
Plasma
108
114
216
116A
112-2
210
206
116
212
212
217

FIG. 2

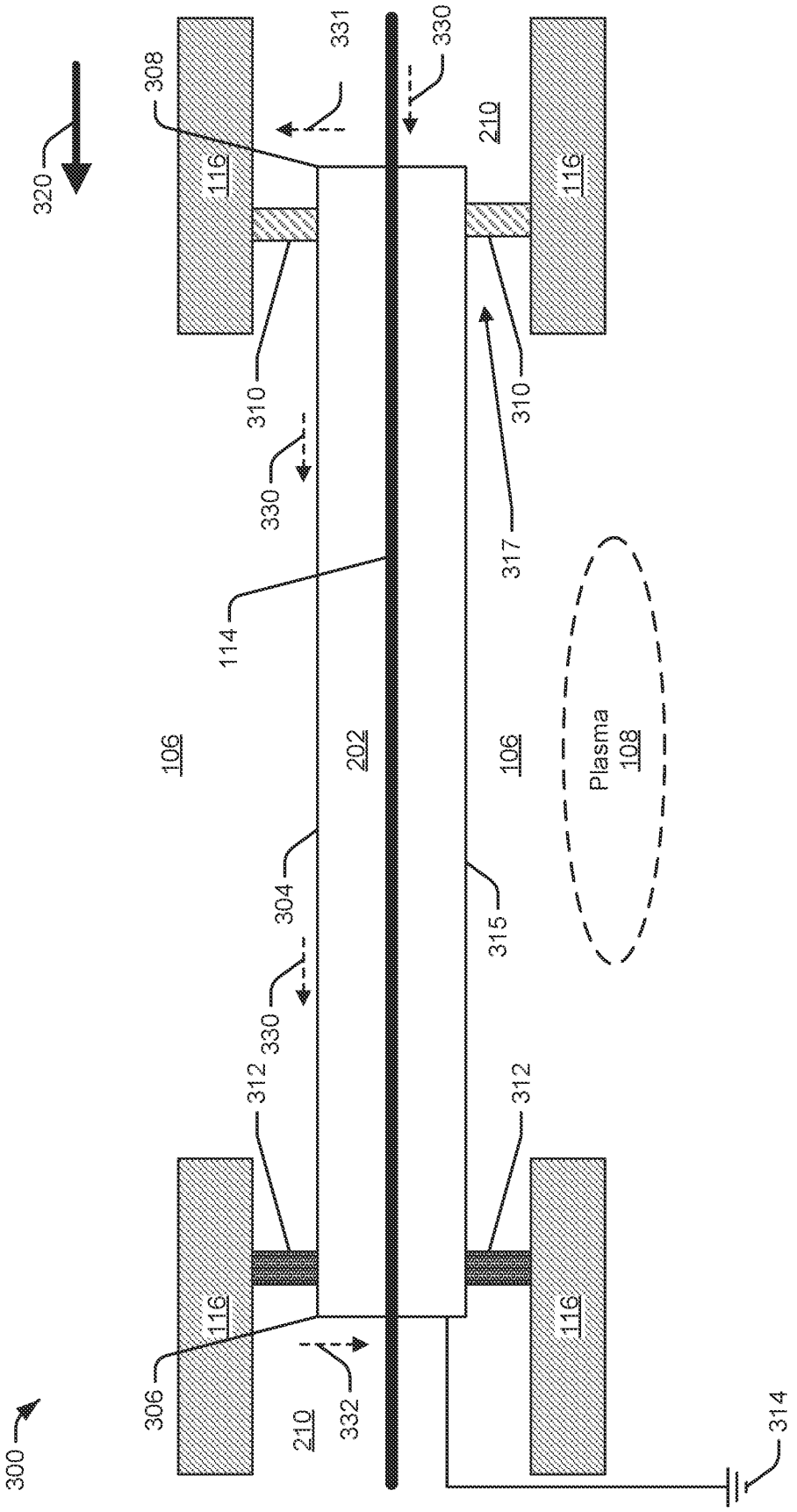

300
320
308
116
331
330
210
116
310
330
310
317
114
106
202
106
Plasma
108
304
315
330
312
312
116
116
306
210
332
314

FIG. 3A

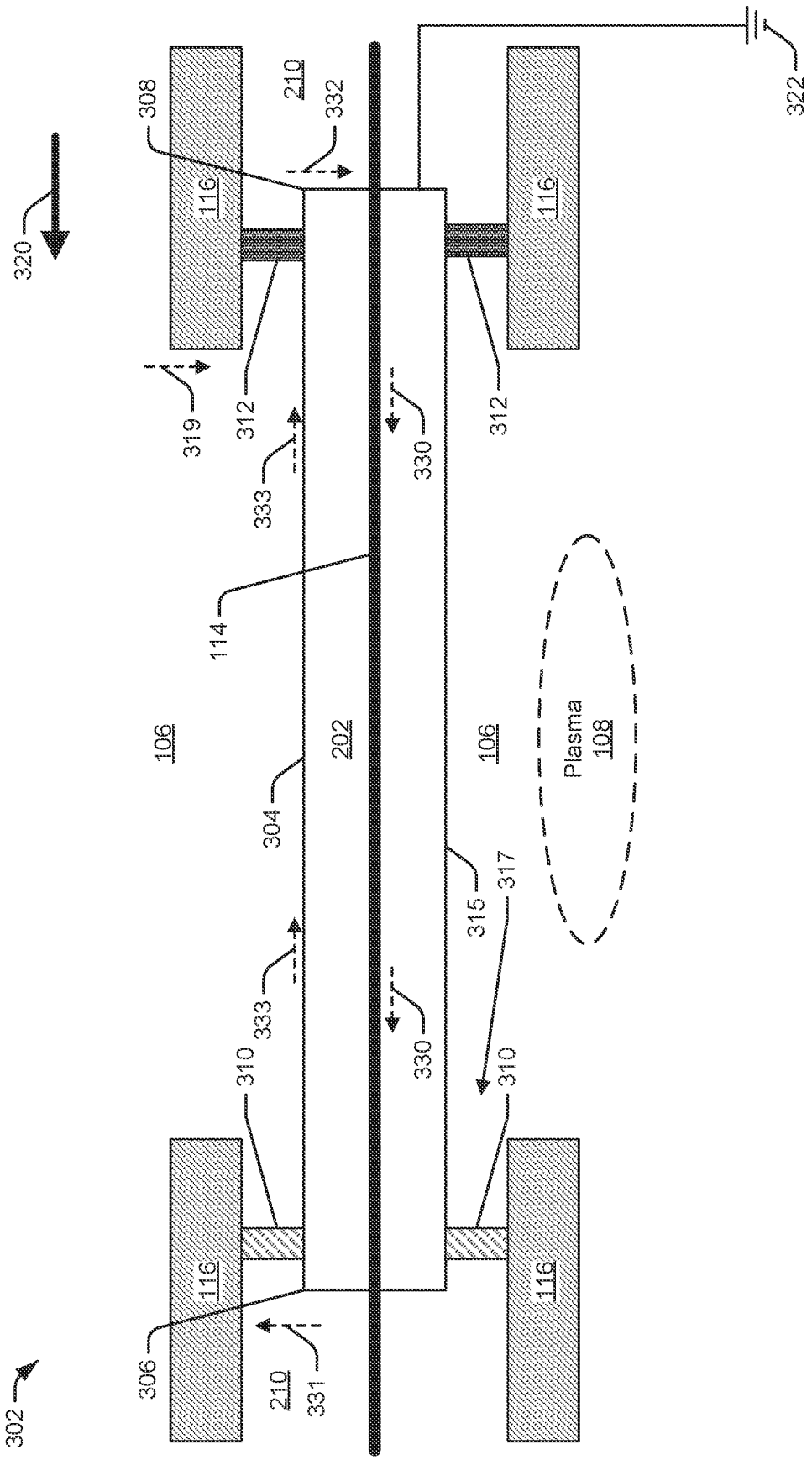

320
308
116
210
332
322
319
312
330
333
114
106
202
304
315
317
Plasma
108
310
306
331
302

FIG. 3B

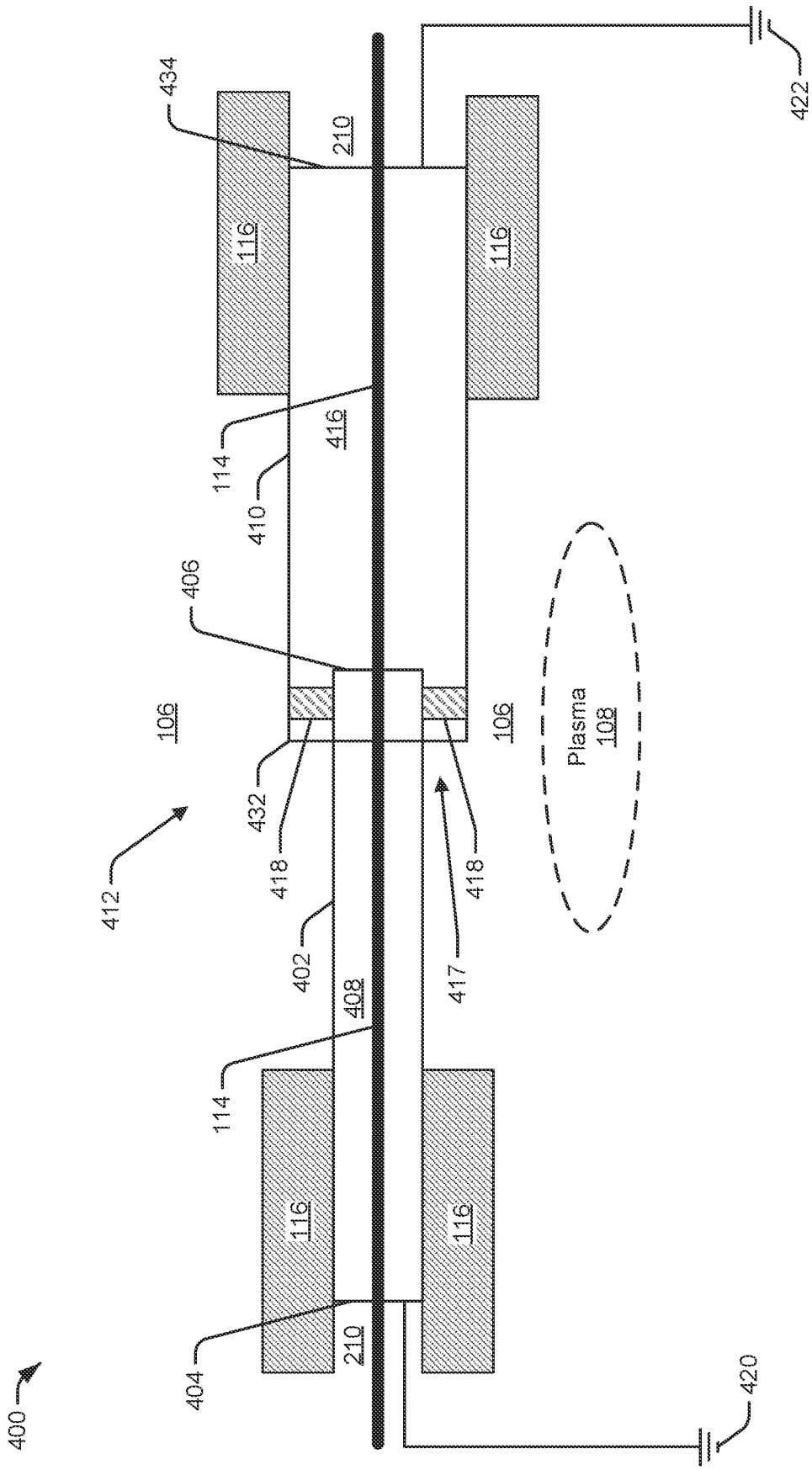

400
404
210
116
116
114
408
402
412
106
432
418
406
434
210
116
116
114
416
410
106
418
417
Plasma
108
420
422

FIG. 4

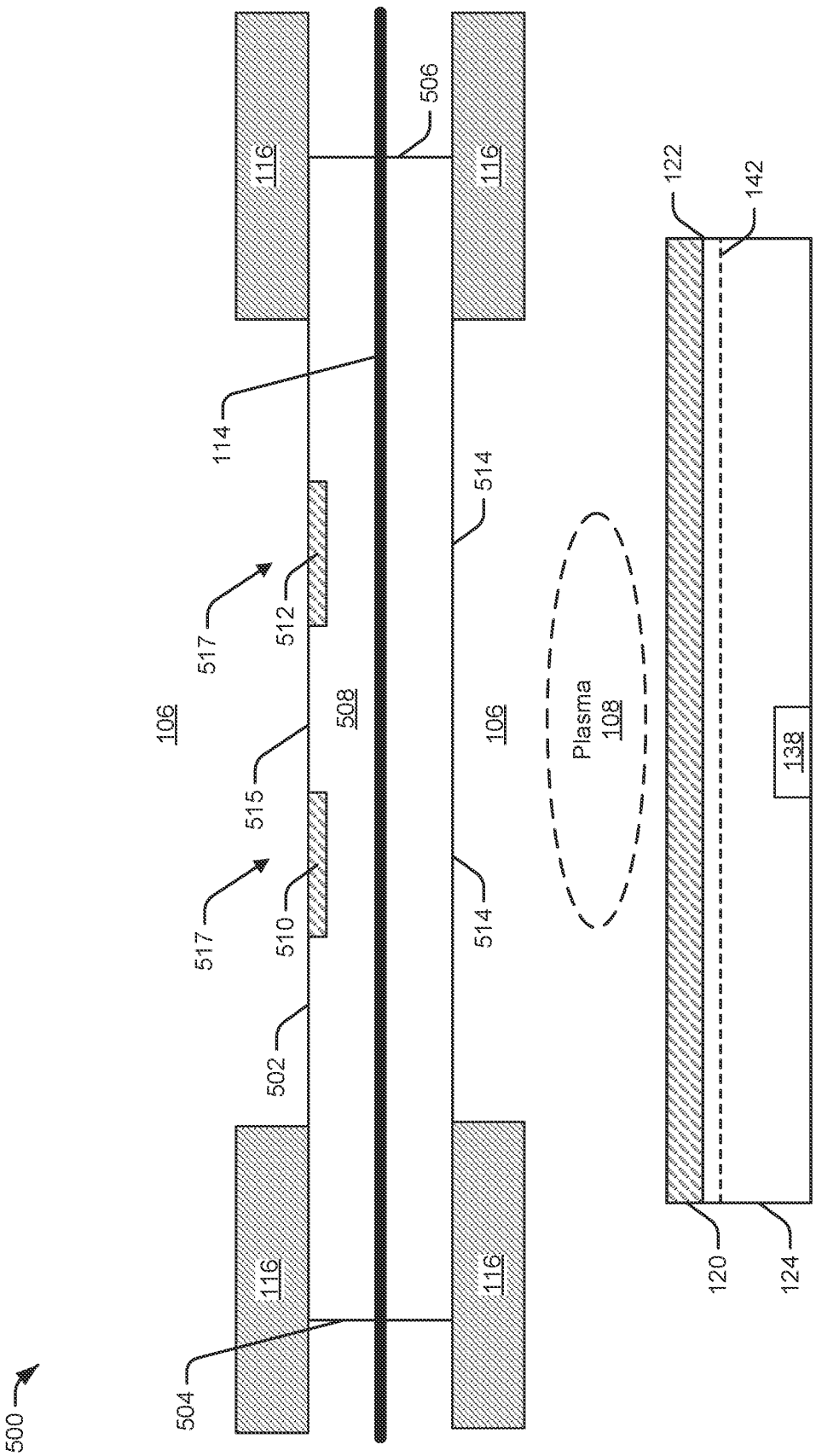

500
504
116
116
116
116
506
114
514
517
512
508
515
517
510
502
514
106
106
Plasma
108
122
142
138
120
124

FIG. 5

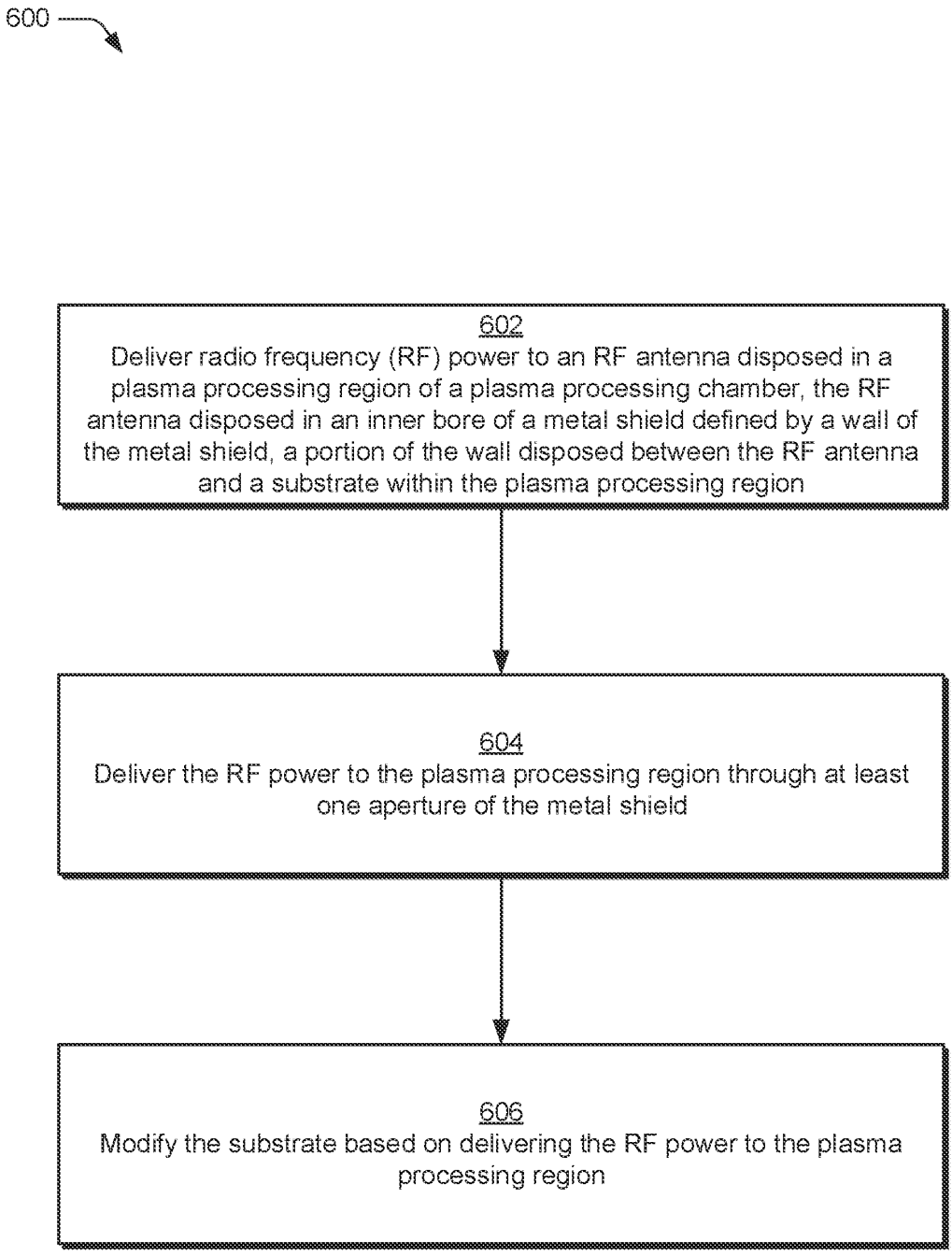

600
602
Deliver radio frequency (RF) power to an RF antenna disposed in a plasma processing region of a plasma processing chamber, the RF antenna disposed in an inner bore of a metal shield defined by a wall of the metal shield, a portion of the wall disposed between the RF antenna and a substrate within the plasma processing region
604
Deliver the RF power to the plasma processing region through at least one aperture of the metal shield
606
Modify the substrate based on delivering the RF power to the plasma processing region

FIG. 6